

CBR08C849DAGAC

General Information

Series

Style

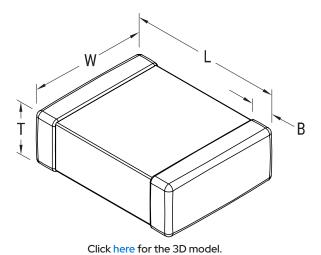
Description

CBR-SMD RF COG, Ceramic, 8.4 pF, +/-0.5 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805

CBR-SMD RF COG

SMD, Fixed, RF, Ultra High Q,

SMD Chip



Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No 12.03 mg Typical Component Weight Notes Solder Wave or Solder Reflow. Shelf Life 78 Weeks MSL 1

| Dimensions | |
|------------|-----------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| т | 0.85mm +/-0.1mm |
| В | 0.5mm +/-0.2mm |

| Packaging Specifications |
|--------------------------|
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Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 8.4 pF |
| Tolerance | +/-0.5 pF |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Dissipation Factor | 0.176% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 568 |

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